

# Patent Abstracts of Japan

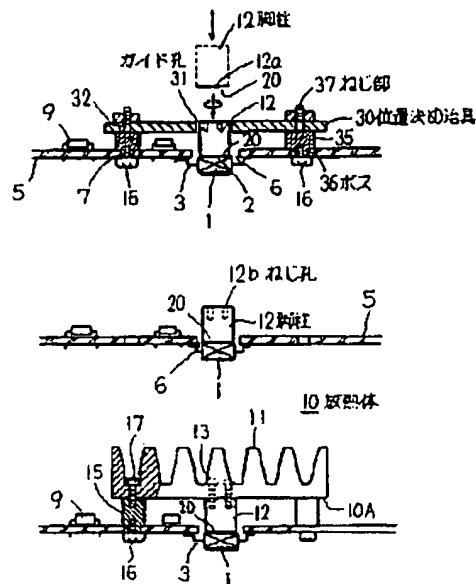
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TITLE : MOUNTING METHOD FOR HEAT RADIATOR OF SEMICONDUCTOR COMPONENT



ABSTRACT : PURPOSE: To obtain a mounting method for a heat radiator having high cooling performance and no loss of insulation of a pattern, etc., of a printed circuit board by pressing the end face of a leg post coated with conductive adhesive to the rear surface of a package, rotating the post, bringing the rear surface of the radiator, after the adhesive is cured, into close contact with the upper end of the post, and clamping the radiator at the post with a small screw.

CONSTITUTION: A leg post 12 coated with a small mount of conductive adhesive 20 on the end face 12a of a leg post is inserted into a guide hole 31, and the post 12 is rotated laterally several times while pressing the end face 12a to the rear surface 2 of a package. It is left to stand for in this state to cure the adhesive 20, and the post 12 is secured to a semiconductor component 1. When the adhesive 20 is completely cured, a positioning jig 30 is removed, and a supporting post 35 is then removed from a printed circuit board 5. After an internal post 15 is inserted into the board 5, a heat radiator 10 is placed on the upper end of the post 15, and the center of the rear surface 10A of the radiator is disposed on the upper end of the post 12. The four corners of the radiator 10 are clamped to the posts 15 with small screws 17. Then, a small screw 13 is inserted into the hole of the radiator 10, engaged with threaded hole 12b of the post 12, and the rear surface 10A is brought into close contact with the upper end of the post 12.

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